ASSOCIATION CONNECT ELECTRONICS INDUST.	© Copyright 2005. IPC, I	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Ty http://www.ipc.org/IPC-175x Distribut														
upplier Infor	rmation															
Company name*			Company unique ID			ī	Unique ID Authority					Response Date*				
onsemi					ļ								2024-05-09			
Contact Name Title - Contact				ct	I			Phone - Contact*					Email - Contact*			
Product-Env-Stewards Pro				Product Enviro Compliance			NA				Prod	Product-Env-Stewards@onsemi.com				
Authorized Representative* Title -				Fitle - Representative			Phone - Representative*				Emai	Email - Representative*				
Product-Env-Ste	wards	I	Product Enviro Compliance				NA				Prod	Product-Env-Stewards@onsemi.com				
Reque	quester Item Number Mfr Item		em Number Mfr Item Name						Manufacturing Site MY1		Weig	tht*	UOM	Unit Type		
		NCS210RM		RMUTAG CURRENT SENSE AMP G=200							3.53		mg	Each		
1anufacturin	g Proccess Information	1														
Termin	erminal Plating / Grid Array Material		Terminal Base Alloy J		J-STD-020 MS	L Rating	Peak Process Body Temperature		Max Time at Peak Tempera		rature	are Number of Reflow Cycles		eles		
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 1		1		260		C 30		sec	seconds		3		
Comments							•				•		•			
vel 1 - maximun	n time at peak temperature d	luring solde	ering is 10-3	0 seconds												
	ation regarding material com															

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.32	mg	Supplier	Silicon (Si)	7440-21-3		0.32	mg
Die Attach	0.1	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.065	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.035	mg
Lead Frame	0.59	mg	Supplier	Zinc (Zn)	7440-66-6		0.0007	mg
			Supplier	Iron (Fe)	7439-89-6		0.0139	mg
			Supplier	Copper (Cu)	7440-50-8		0.5752	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0002	mg
Mold Compound-Black	2.49	mg	Supplier	Epoxy resins	129915-35-1		0.1245	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.1245	mg
			Supplier	Carbon Black (C)	1333-86-4		0.01	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.0573	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		2.1165	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0573	mg
Plating	0.01	mg	Supplier	Palladium (Pd)	7440-05-3		0.0003	mg
			В	Nickel (Ni)	7440-02-0		0.0096	mg
			Supplier	Gold (Au)	7440-57-5		0.0001	mg
Wire Bond - Au	0.02	mg	Supplier	Gold (Au)	7440-57-5		0.02	mg